

FlacheSAN2N12C-D5



FEATURES

- All NVMe Flash Array supports Dual Intel® Xeon® SP Scalable Processors (Skylake)
- Supports 12x front accessible hot-swap NVMe PCIe3 x8 Add-in-Cards
- Up to 60GB/s (480 Gigabits/s) throughput and 12 Millions IOPS through RDMA
- Supports 4x full height PCIe3 x16 PCIe slots (Optional: 6x PCIe3 x16 slots)
- Symmetrically balance design each CPU managing half NVMe and NIC

SPECIFICATIONS

Processor Support	Supports Dual Intel® Xeon® SP (Skylake) up to 205W TDP socket LGA3647
Chipset	Intel® C621 chipset
Memory Support	Support 16x DDR4 ECC RDIMM/LRDIMM 2133/2400/2666MT/s max. 2TB capacity
Expansion Slot	Supports 4x full height PCIe3 x16 PCIe slots (Optional: 6x PCIe3 x16 slots)
Storage	12x Low Profile Front Hot-Swappable PCIe3 x8 NVMe Add-in-Card
Drive Bays	12x PCIe3 x8 slots, 2x 2.5" internal drive bays and 2x 2.5" 7mm rear hot-swap drive bays
Network	2x GbE RJ45 LAN ports, 1x IPMI Management RJ45 port
Power	1+1 1600W AC/DC 80 Plus Platinum Redundant PSU



Supported OS	Windows Server 2016, 2012 R2, RHEL 6.9/7.3, SLES 11.4, Ubuntu 16.04.2 LTS, VMWare ESXi 6.5; For other OS please contact us
Front Panel	Power On/OFF with LED, reset Switch, NMI switch, Locate Switch with LED, 4xLAN LED, Warning LED 1x USB 3.0
Rear I/O	1x DB15 VGA, 2x RJ45 1GbE, 2x 10GbE SFP+, 1x RJ45 MGMT, 2x USB 3.0
Cooling	4x 80mm high speed fans
Other Features	Optional Intel® VROC NVMe RAID
Weight	Gross: 29KG/64LBS; Net: 25KG/55LBS
Dimension	System: 30"x19"x3.5" (LxWxH) Packaging: 37"x 24"x10" (LxWxH)
Logistic	HTS Code: 8473 30 5100; ECCN: 4A994
Environmental	Operating Temperature: 0°C to 35°C Non-Operating Temperature: -20°C to 70°C Humidity: 5% to 95% non-condensing
Compliance	CE, FCC Class A, RoHS 6/6 compliant

ORDERING INFO

BB212NCD5TY18-A 2U 12 NVMe ADD-IN-CARD PCIE x8 DUAL XEON SP 1200W HRP

